Abstracts

Modeling and characterization of interconnects and IC packages by FDTD 3D simulation

M. Falconer and V. Tripathi. "Modeling and characterization of interconnects and IC packages by FDTD 3D simulation." 1997 MTT-S International Microwave Symposium Digest 3. (1997 Vol. III [MWSYM]): 1733-1736.

Time domain electromagnetic simulation of 3-D lossy interconnect coupling and ground bounce in a typical IC package is presented. The FDTD simulation tool is also proposed and used as a Virtual TDR (V-TDR) to extract the circuit models associated with complex 3D structures.

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